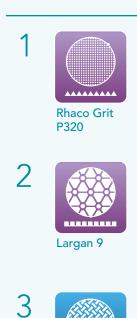
Aka-Brief #13 Electronic Components







Water







20 N









9 µm

3 µm

















150 rpm











Chemal*



Fumed Silica 0.2 µm Alkaline**



150 rpm



15 N



2:00 min



BF, 50x

Times are stated for a 300 mm preparation system and forces for an individual 40 mm dia. sample.

On a 250 mm system the times should be increased by 30%, on a 200 mm system by 100%.

With larger samples the force should be increased, with smaller samples decreased.

The rotational speed of the head (sample holder or sample mover plate) used is 150 rpm.

Time and force may vary depending on the equipment.

- * Prior to oxide polishing the polishing cloth should be wetted with water until the holder touches the polishing cloth. For the last 10 seconds of the oxide polishing step, the polishing cloth should be flushed with water to clean both sample(s) and polishing cloth.
- ** 96 ml Fumed Silica, 2 ml H₂O₂ (30%), 2 ml NH₄OH (25%)

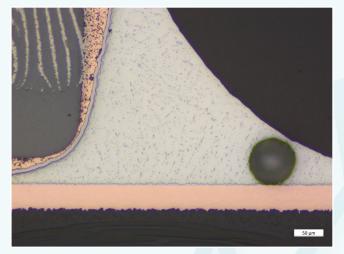
The mixture should be used fresh (within a couple of hours) and stirred regularly.

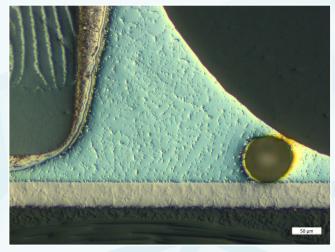
Please make sure that all necessary safety precautions are taken when handling chemicals.



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FINAL RESULT



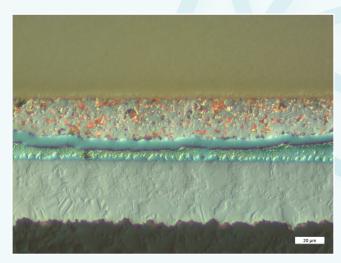




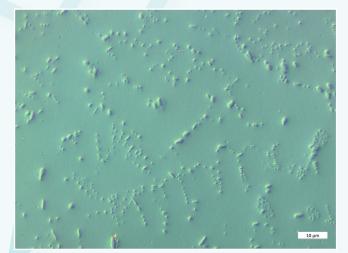
BF, 200x

DIC, 200x

POL + Lambda Compensator, 200x







DIC, 500x

DIC, 500x

DIC, 1000x

